# A Low Cost Packaging/Testing Procedure for Manufacturing GaAs MMIC (1987 Vol. I [MWSYM])

*R. Esfandiari, D. Yang, S. Chan, S. Lin and R.K. Ellis. "A Low Cost Packaging/Testing Procedure for Manufacturing GaAs MMIC (1987 Vol. I [MWSYM])." 1987 MTT-S International Microwave Symposium Digest 87.1 (1987 Vol. I [MWSYM]): 229-231.*

The development of a low cost, high throughput testing/packaging procedure for GaAs MMIC is described. Automated on-wafer RF and DC testing is essential for volume production of MMIC chips. However, most MMIC circuits cannot be tested at wafer level due to lack of proper RF test environment. The proposed frame tape chip carrier approach takes full advantage of the RF probe system. This technique reduces the high cost of RF package measurements and reliability testing. The measurement and packaging is demonstrated on several MMIC chips. It can easily be automated for high volume production.

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